

**Some Suggestions used by some customers**

(These temps are optional and are just examples, these are not part of the BIRD 8888 Official manual of use and each single customer must realize , kind of chip, solder, weather conditions are variables for any profile and those must be counted to do anything with the programing of the machine )

**Lead Solder Temp Curves (AGAIN ARE EXAMPLES)**

41\*41 BGA Solder temperatures setting:

	<b>Preheating section</b>	<b>Temperature-holding section</b>	<b>Heating-up section</b>	<b>Solder section 1</b>	<b>Solder section 2</b>	<b>Temperature-drop section</b>
<b>Top Heating</b>	160	185	210	220		
<b>Constant Temperature Time</b>	30	30	35	40		
<b>Bottom Heating</b>	165	195	215	230		
<b>Constant Temperature Time</b>	30	30	35	60		
<b>Infrared Time</b>	110	120	130	140		
<b>Constant Temperature Time</b>	30	30	35	60		
<b>Slope</b>	2. 0	2. 0	2. 0	2. 0		

38\*38 BGA Solder Temperature Setting:

	Preheating section	Temperature-holding section	Heating-up section	Solder section 1	Solder section 2	Temperature-drop section
<b>Top Heating</b>	160	185	210	225		
<b>Constant Temperature Time</b>	30	30	35	40		
<b>Bottom Heating</b>	165	190	215	230		
<b>Constant Temperature Time</b>	30	30	35	40		
<b>Infrared Time</b>	110	120	130	140		
<b>Constant Temperature Time</b>	30	30	35	40		
<b>Slope</b>	2	2	2	2		

31\*31 BGA Solder Temperature Setting:

	Preheating section	Temperature-holding section	Heating-up section	Solder section 1	Solder section 2	Temperature-drop section
<b>Top Heating</b>	160	180	200	215		
<b>Constant Temperature Time</b>	30	30	35	40		
<b>Bottom Heating</b>	160	180	200	215		
<b>Constant Temperature Time</b>	30	30	35	40		
<b>Infrared</b>	110	120	130	140		

<b>Time</b>						
<b>Constant Temperature Time</b>	30	30	35	40		
<b>Slope</b>	2	2	2	2		

### Lead-free temperature curve solder

41\*41 BGA Solder temperatures setting:

	<b>Preheating section</b>	<b>Temperature-holding section</b>	<b>Heating-up section</b>	<b>Solder section 1</b>	<b>Solder section 2</b>	<b>Temperature-drop section</b>
<b>Top Heating</b>	165	190	225	245	255	
<b>Constant Temperature Time</b>	30	30	35	55	25	
<b>Bottom Heating</b>	165	190	225	245	255	
<b>Constant Temperature Time</b>	30	30	35	55	25	
<b>Infrared Time</b>	120	130	140	150	160	
<b>Constant Temperature Time</b>	30	30	35	55	25	
<b>Slope</b>	2	2	2	2	2	

38\*38 BGA Solder temperatures setting:

	Preheating section	Temperature -holding section	Heating-up section	Solder section 1	Solder section 2	Temperature -drop section
<b>Top Heating</b>	165	190	225	245	250	
<b>Constant Temperature Time</b>	30	30	35	45	25	
<b>Bottom Heating</b>	165	190	225	245	250	
<b>Constant Temperature Time</b>	30	30	35	45	25	
<b>Infrared Time</b>	120	130	140	150	160	
<b>Constant Temperature Time</b>	30	30	35	45	25	
<b>Slope</b>	2	2	2	2	2	

### 31\*31 BGA Solder Temperature Setting

	<b>Preheating section</b>	<b>Temperature -holding section</b>	<b>Heating -up section</b>	<b>Solder section 1</b>	<b>Solder section 2</b>	<b>Temperature -drop section</b>
<b>Top Heating</b>	165	190	220	240	245	
<b>Constant Temperature Time</b>	30	30	35	40	20	
<b>Bottom Heating</b>	165	190	220	240	245	
<b>Constant Temperature Time</b>	30	30	35	40	20	
<b>Infrared Time</b>	120	130	140	150	160	
<b>Constant Temperature Time</b>	30	30	35	40	20	
<b>Slope</b>	2	2	2	2	2	

If you want to dismantle BGA, it is enough to set the value of temperature-drop section as 0.